

AVAGO TECHNOLOGIES, LTD.
4380 Ziegler Road
Fort Collins, Colorado 80525

ATTORNEY DOCKET NO. 10030899-1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): R. Shane Fazzio

Serial No.: 10/807,417

Examiner: Monica Lewis

Filing Date: March 23, 2004

Group Art Unit: 2822

Title: Microcap Wafer Bonding Apparatus

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria VA 22313-1450

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

Sir:

Transmitted herewith is/are the following in the above-identified application:

- ☒ Response/Amendment ☒ Petition to extend time to respond
☐ New fee as calculated below ☐ Supplemental Declaration
☐ No additional fee (Address envelope to "Mail Stop Amendments")
☒ Other: Response to Notice of Non-Compliant Amendment (Fee \$)


CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS		MINUS		= 0	X 50	\$ 0
INDEP. CLAIMS		MINUS		= 0	X 210	\$ 0
<input type="checkbox"/> FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					+ 370	\$ 0
EXTENSION FEE	1 st MONTH 120.00 <input checked="" type="checkbox"/>	2 nd MONTH 460.00 <input type="checkbox"/>	3 rd MONTH 1050.00 <input type="checkbox"/>	4 th MONTH 1640.00 <input type="checkbox"/>		\$ 120
OTHER FEES						\$ 0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$ 120

Charge \$ 120 to Deposit Account 50-3718. At any time during the pendency of this application, please charge any fees required or credit any over payment to Deposit Account 50-3718 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 50-3718 under 37 CFR 1.16, 1.17, 1.19, 1.20 and 1.21. A duplicate copy of this transmittal letter is enclosed.

Respectfully submitted,

R. Shane Fazzio

By


Thomas F. Woods
Attorney/Agent for Applicant(s)

I hereby certify that this paper is being electronically transmitted to the Commissioner for Patents on the date shown below.

Date of Transmission: October 9, 2007

Typed Name: Thomas F. Woods

Signature: 

Reg. No. 36,726

Date: October 9, 2007

Telephone No. (303) 823-6560

U.S. Patent Appln. Ser. No. 10/807,417 entitled "Microcap Wafer Bonding Apparatus " to Fazzio;
Avago Technologies Attorney Docket No. 10030899-1; Woods Patent Law Docket No. P AVG
188.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: R. Shane Fazzio

Examiner Name: Monica Lewis

Serial No.: 10/807,417

Group Art Unit: 2822

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Attorney Docket No.: 10030899-1

Confirmation No.: 3854

Title: Microcap Wafer Bonding Apparatus

**SECOND PRELIMINARY AMENDMENT AND RESPONSE TO
NOTICE OF NON-COMPLIANT AMENDMENT**


Commissioner for Patents
P.O. Box 1450
Arlington, VA 22313-1450

Sir:

In response to the Notice of Non-Compliant Amendment dated August 29, 2007, and further to a Request for Continuing Examination submitted on August 27, 2007, Applicants respectfully request entry of the second set of preliminary amendments set forth herein, and allowance of the above-identified patent application as amended herein:

DATE OF DEPOSIT: October 9, 2007

CERTIFICATE OF ELECTRONIC DEPOSIT: I hereby certify that all paper(s) described herein are being filed electronically with the United States Patent and Trademark Office on the date indicated above and addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Signature: 
Printed Name: Thomas F. Woods, Reg. No. 36,726